

**P-Channel Enhancement Mode Mosfet**

**GENERAL DESCRIPTION**

The ME7835 P-Channel logic enhancement mode power field effect transistors are produced using high cell density, DMOS trench technology. This high density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage application such as cellular phone and notebook computer power management and other battery powered circuits where high-side switching , and low in-line power loss are needed in a very small outline surface mount package.

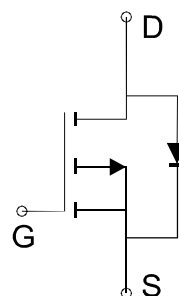
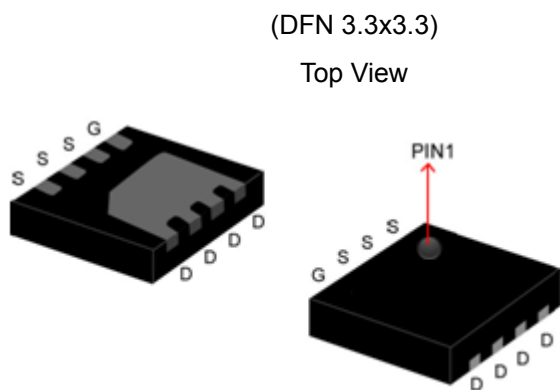
**FEATURES**

- RDS(ON) ≤ 18mΩ@VGS=-10V
- RDS(ON) ≤ 36mΩ@VGS=-4.5V

**APPLICATIONS**

- Power Management in Note book
- Portable Equipment
- Battery Powered System
- Load Switch
- DSC

**PIN CONFIGURATION**



Ordering Information: ME7835 (Pb-free)

ME7835-G (Green product-Halogen free)

**Absolute Maximum Ratings (Tj=25°C Unless Otherwise Noted)**

Parameter	Symbol	Maximum	Unit
Drain-Source Voltage	V <sub>DSS</sub>	-30	V
Gate-Source Voltage	V <sub>GSS</sub>	±25	V
Continuous Drain Current	I <sub>D</sub>	T <sub>A</sub> =25°C	-11.5
		T <sub>A</sub> =70°C	-9.2
Pulsed Drain Current	I <sub>DM</sub>	-46	A
Maximum Power Dissipation	P <sub>D</sub>	T <sub>A</sub> =25°C	3.8
		T <sub>A</sub> =70°C	2.4
Operating Junction Temperature	T <sub>J</sub>	-55 to 150	°C
Thermal Resistance-Junction to Ambient*	R <sub>θJA</sub>	33	°C/W

\*The device mounted on 1in<sup>2</sup> FR4 board with 2 oz copper



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**Electrical Characteristics** ( $T_A=25^{\circ}\text{C}$  Unless Otherwise Specified)

Symbol	Parameter	Limit	Min	Typ	Max	Unit
<b>STATIC</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-30			V
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1		-3	V
$I_{GSS}$	Gate Leakage Current	$V_{DS}=0V, V_{GS}=\pm 25V$			$\pm 100$	nA
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=-30V, V_{GS}=0V$			-1	$\mu A$
$R_{DS(on)}$	Drain-Source On-State Resistance <sup>a</sup>	$V_{GS}=-10V, I_D=-8.5A$		15	18	m $\Omega$
		$V_{GS}=-4.5V, I_D=-6.3A$		27	36	
$V_{SD}$	Diode Forward Voltage	$I_S=-8.5A, V_{GS}=0V$		0.85	1.2	V
<b>DYNAMIC</b>						
$Q_g$	Total Gate Charge (-10V)	$V_{DS}=-15V, V_{GS}=-10V,$ $I_D=-8.5A$		28		nC
$Q_g$	Total Gate Charge (-4.5V)			14		
$Q_{gs}$	Gate-Source Charge			6		
$Q_{gd}$	Gate-Drain Charge			6.5		
$C_{iss}$	Input Capacitance	$V_{DS}=-15V, V_{GS}=0V, f=1MHz$		1180		pF
$C_{oss}$	Output Capacitance			223		
$C_{rss}$	Reverse Transfer Capacitance			73		
$t_{d(on)}$	Turn-On Delay Time	$V_{DS}=-15V, R_L=15\Omega$ $R_{GEN}=6\Omega, V_{GS}=-10V$		39		ns
$t_r$	Turn-On Rise Time			16		
$t_{d(off)}$	Turn-Off Delay Time			78		
$t_f$	Turn-Off Fall Time			19		

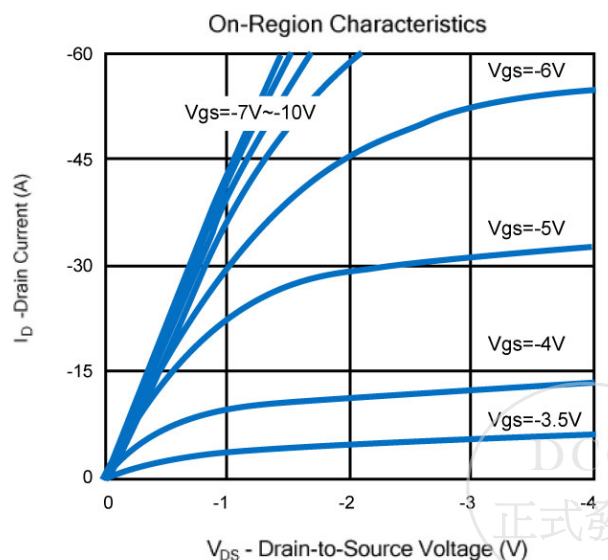
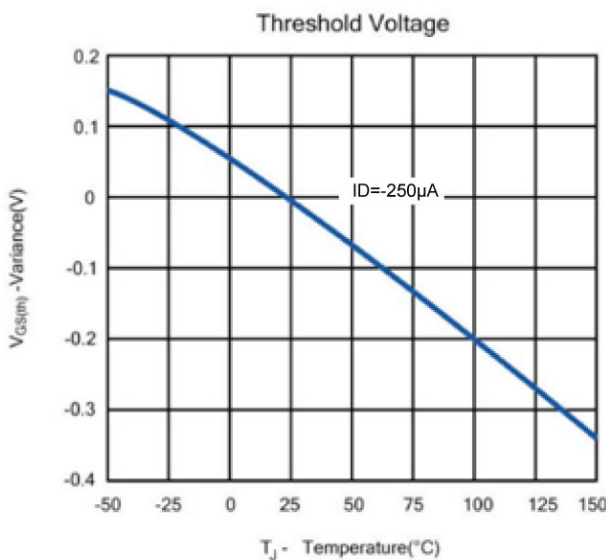
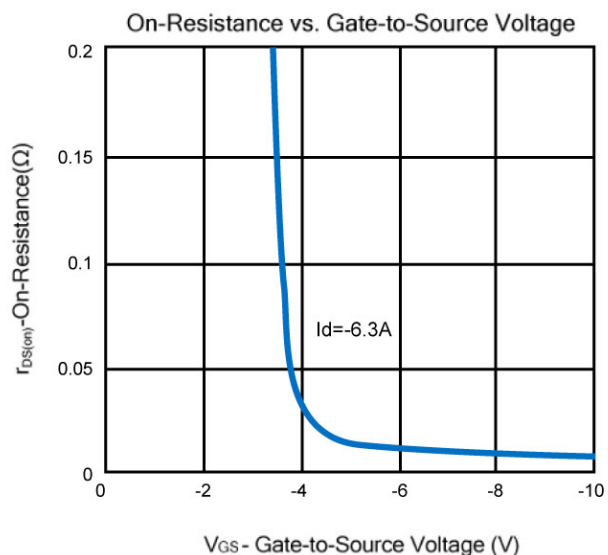
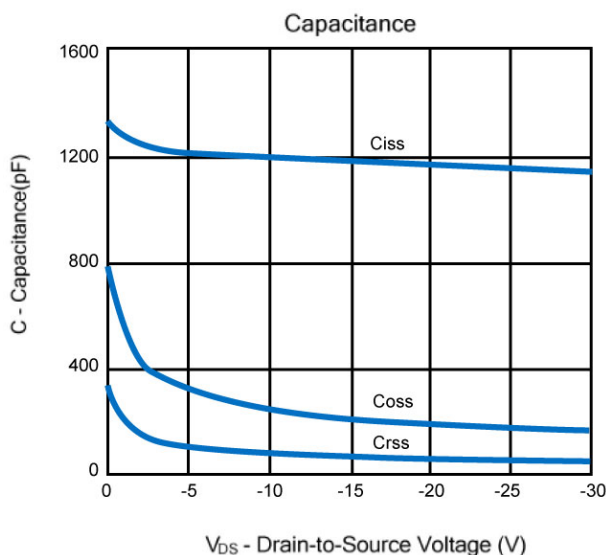
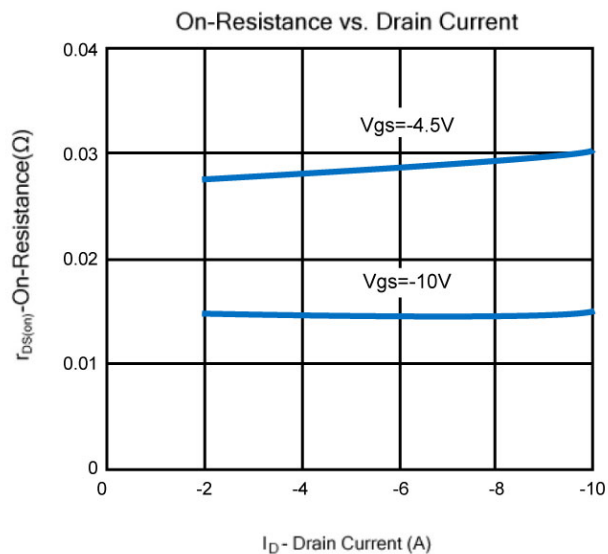
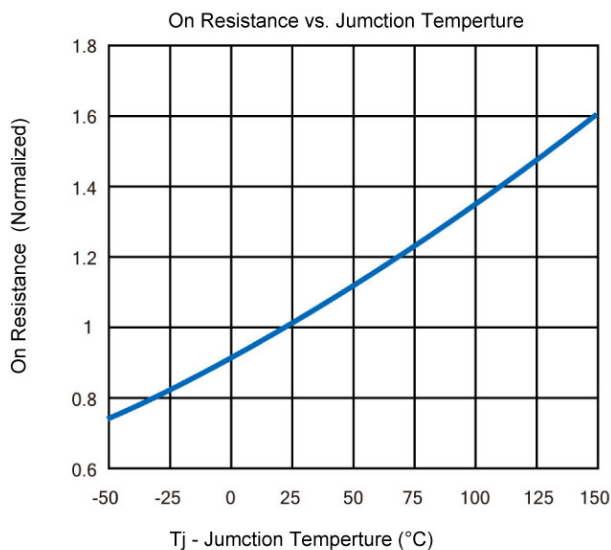
 Note: a. Pulse test: pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ 

b. Matsuki reserves the right to improve product design, functions and reliability without notice.



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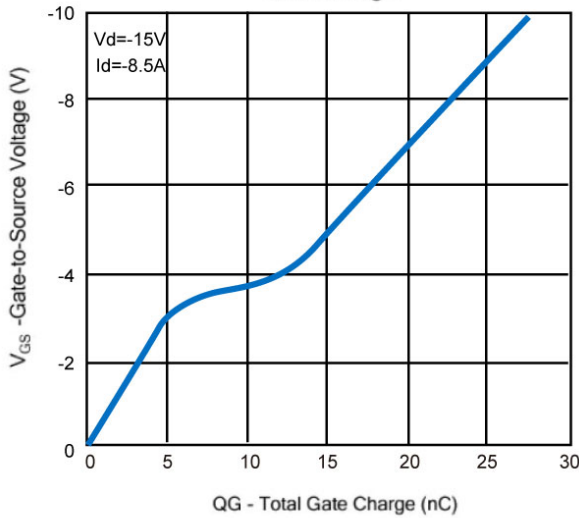
**Typical Characteristics (T<sub>J</sub> = 25°C Noted)**



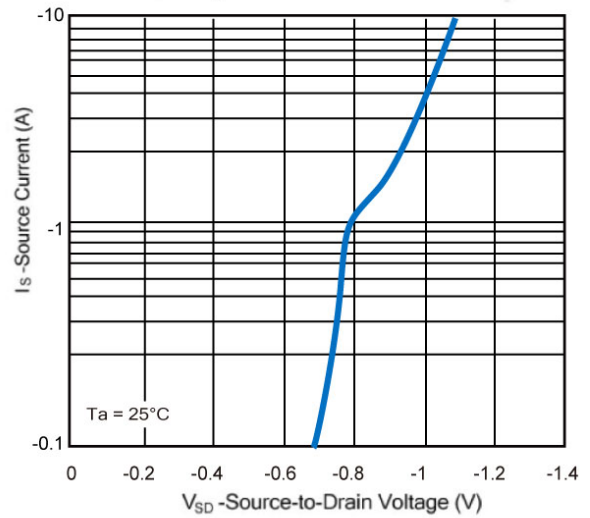
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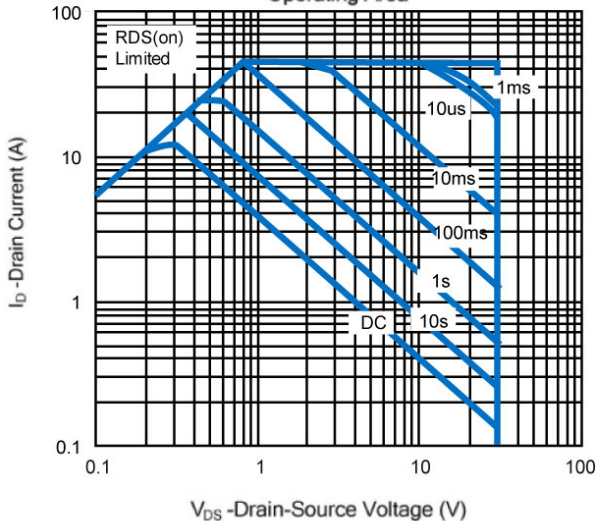
**Gate Charge**



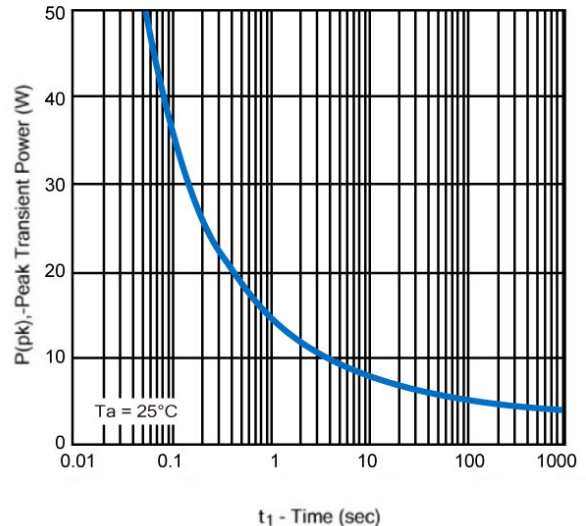
**Body-diode characteristics**



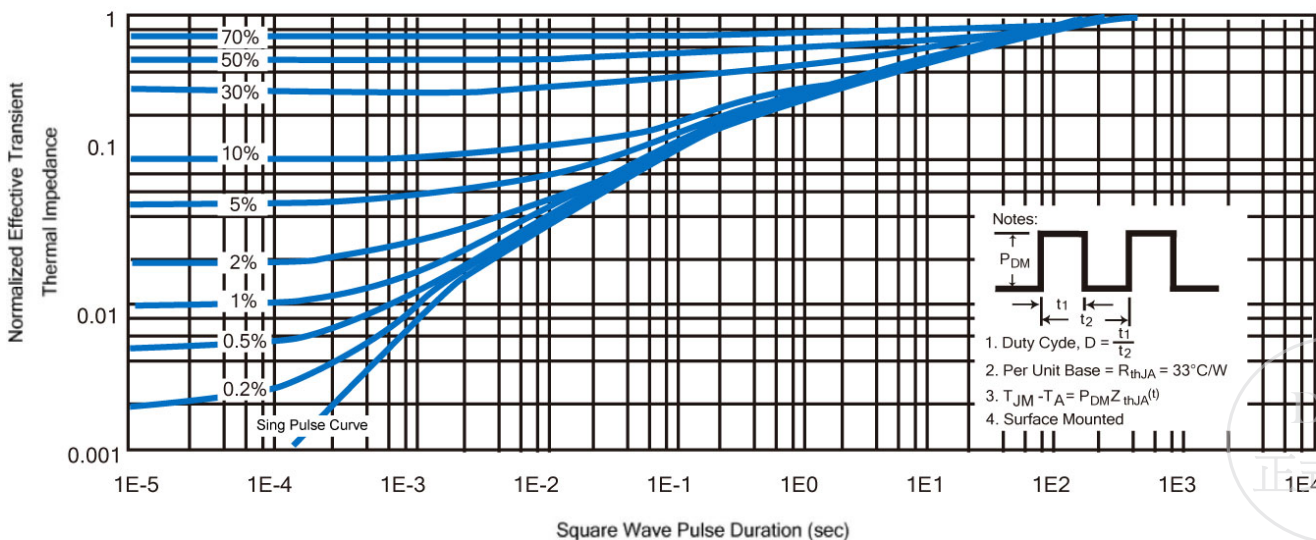
**Maximum Forward Biased Safe Operating Area**



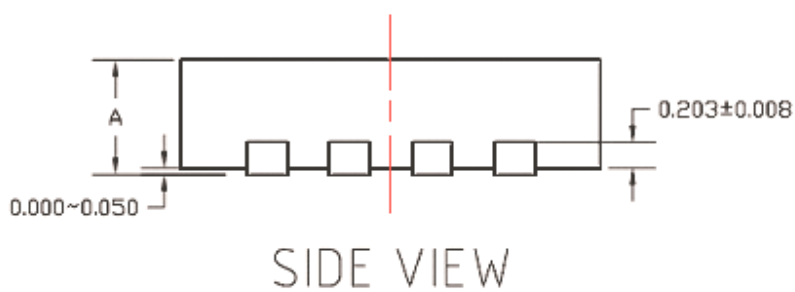
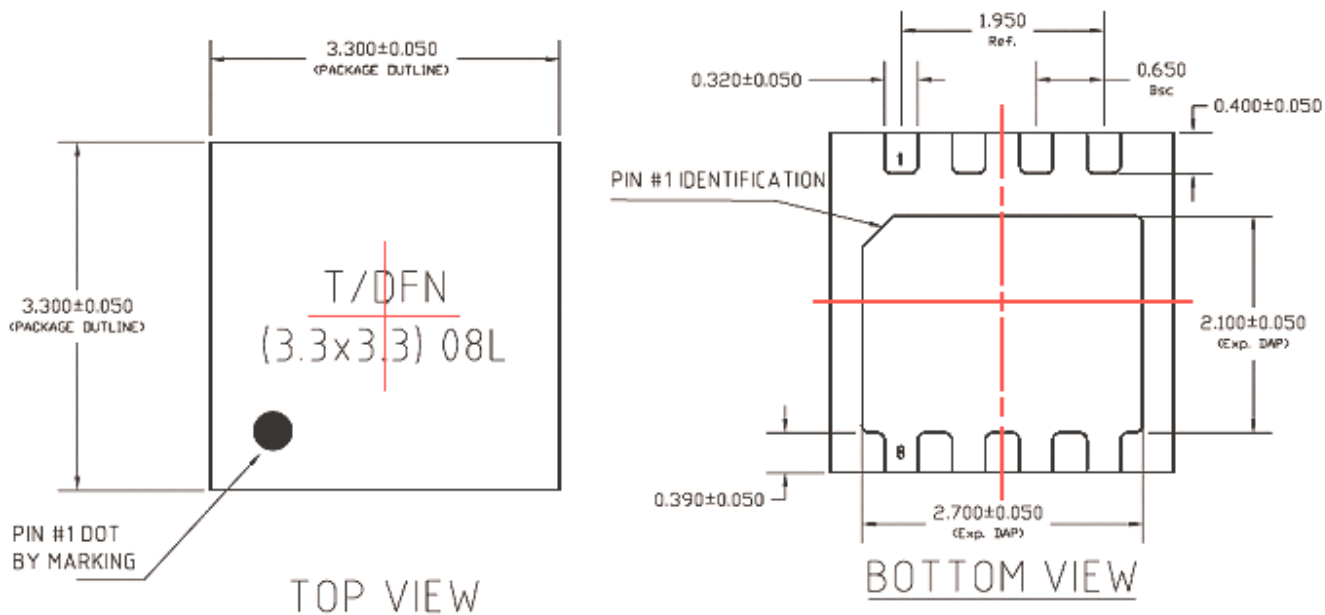
**Single Pulse Maximum Power Dissipation**



**Normalized Thermal Transient Impedance, Junction-to-Ambient**



**DFN 3.3x3.3 Package Outline**



		DFN	TDFN
A	MAX.	1.000	0.800
	NOM.	0.850	0.750
	MIN.	0.800	0.700

Unit : mm

